2SJ0536

Silicon P-channel MOSFET

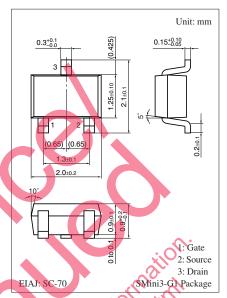
Secondary battery packs (Li ion battery, etc.) For switching circuits

■ Features

- High-speed switching
- S-mini type package, allowing downsizing of the sets and automatic insertion through the tape/magazine packing
- Low voltage drive (V_{th}: -1.0 V to 2.0 V)
- Low ON resistance

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Drain-sourse surrender voltage	V_{DSS}	-30	V
Gate-source voltage (Drain open)	V_{GSO}	±20	V
Drain current	I_D	-100	mA
Peak drain current	I_{DP}	-200	mA
Power dissipation	P_{D}	150	mW
Channel temperature	T _{ch}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



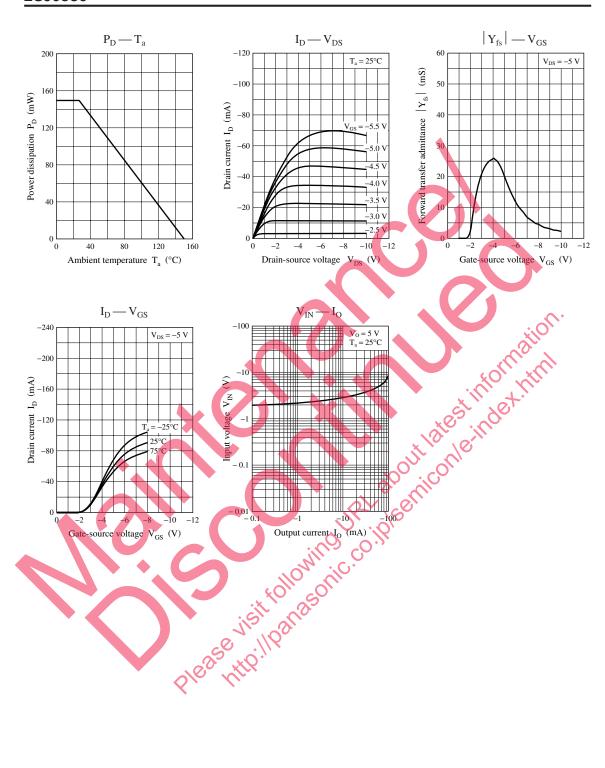
Marking Symbol: 2C

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Drain current	I _D -100	mA		(0)) × (
Peak drain current	I _{DP} -200	mA Marking	Symbol	: 20	Nr.	
Power dissipation	P _D 150	mW	à	· ```\@	*	
Channel temperature	T _{ch} 150	°C	XO'S	100		
Storage temperature	T_{stg} $-55 \text{ to } +15$	0 °C	'o 16			
•		mA Marking mW °C MO C M	COLI			
■ Electrical Characteristics	$T_a = 25^{\circ}C \pm 3^{\circ}C$	35 (1)	<u> </u>			
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Drain-source cutoff current	I_{DSS} $V_{DS} = -$	$30 \text{ V}, \text{ V}_{GS} = 0$			- 0.1	μΑ
Gate-source cutoff current	I_{GSS} $V_{GS} = \pm$	$20 \text{ V, V}_{DS} = 0$			±1.0	μΑ
Gate threshold voltage		$5 \text{ V}, I_D = -1 \mu \text{A}$	-1.0		-2.0	V
Forward transfer admittance	$ Y_{\rm fs} $ $ V_{\rm DS} $	$5 \text{ V, } I_{D} = -10 \text{ mA}$	8			mS
Drain-source ON resistance	$R_{DS(on)}$ $V_{GS} = -$	$5 \text{ V}, 1_{\text{D}} = -10 \text{ mA}$		50	75	Ω
Turn-on time	t_{on} $V_{DD} = R_{L} = 20$	5 V, $V_{GS} = 0$ V ~ -5 V 0Ω		100		μs
Turn-off time	$V_{DD} = R_L = 20$	$^{-5}$ V, $V_{GS} = -5$ V ~ 0 V 0 Ω		25		μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

^{2.} Observe precautions for handling. Electrostatic sensitive devices.



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